

Title (en)

HEAT-SINK DEVICE INTENDED FOR AT LEAST ONE ELECTRONIC COMPONENT AND CORRESPONDING METHOD

Title (de)

KÜHLKÖRPER FÜR MINDESTENS EIN ELEKTRONISCHES BAUTEIL UND ENTSPRECHENDES VERFAHREN

Title (fr)

DISPOSITIF POUR LA DISSIPATION THERMIQUE DESTINE A AU MOINS UN COMPOSANT ELECTRONIQUE ET PROCEDE CORRESPONDANT

Publication

**EP 2625710 A1 20130814 (FR)**

Application

**EP 11773882 A 20110927**

Priority

- FR 1003931 A 20101005
- IB 2011054243 W 20110927

Abstract (en)

[origin: WO2012046161A1] The present invention relates to a heat-sink device intended for at least one electronic component (12), including: heat-sink means; a substrate (11) for the at least one electronic component (12), said substrate covering the heat-sink means; and thermal coupling means provided between the substrate and the heat-sink means and made from a material different from that of the heat-sink means. According to the invention, the heat-sink means consist of a set of independent fins (10), and the thermal-coupling means (13) are made from a heat-conductive polymer material and also serve as mechanical coupling means between the substrate (11) and the fins (10).

IPC 8 full level

**H01L 21/48** (2006.01); **H01L 23/367** (2006.01); **H01L 23/373** (2006.01)

CPC (source: EP US)

**F21V 29/87** (2015.01 - EP US); **H01L 21/4882** (2013.01 - EP US); **H01L 23/367** (2013.01 - EP US); **H01L 23/3672** (2013.01 - EP US); **H01L 23/3737** (2013.01 - EP US); **H05K 3/30** (2013.01 - US); **H05K 7/2039** (2013.01 - US); **F21V 29/717** (2015.01 - EP US); **F21Y 2115/10** (2016.07 - EP US); **H01L 2924/0002** (2013.01 - EP US); **Y10T 29/4913** (2015.01 - EP US)

Citation (search report)

See references of WO 2012046161A1

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

DOCDB simple family (publication)

**FR 2965699 A1 20120406**; **FR 2965699 B1 20130329**; EP 2625710 A1 20130814; US 2013322019 A1 20131205; US 9622382 B2 20170411; WO 2012046161 A1 20120412

DOCDB simple family (application)

**FR 1003931 A 20101005**; EP 11773882 A 20110927; IB 2011054243 W 20110927; US 201113877752 A 20110927